DATA SHEET

74ABT2241

Octal buffer with 30Ω series termination resistors; (3-State)

Product specification

1996 Sep 30

IC23 Data Handbook

PHILIPS

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Octal buffer with 30Ω series termination resistors (3-State)

74ABT2241

FEATURES

- Octal bus interface
- 3-State buffers
- Power-up 3-State
- Output capability: +12mA/–32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT2241 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT2241 device is an octal buffer that is ideal for driving bus lines. The device features two Output Enables (1$\overline{OE}$, 2OE), each controlling four of the 3-State outputs.

The 74ABT2241 is designed with 30Ω series resistance in both the High and Low states of the output. The design reduces line noise in applications such as memory address drivers, clock drivers, and bus receivers/transceivers.
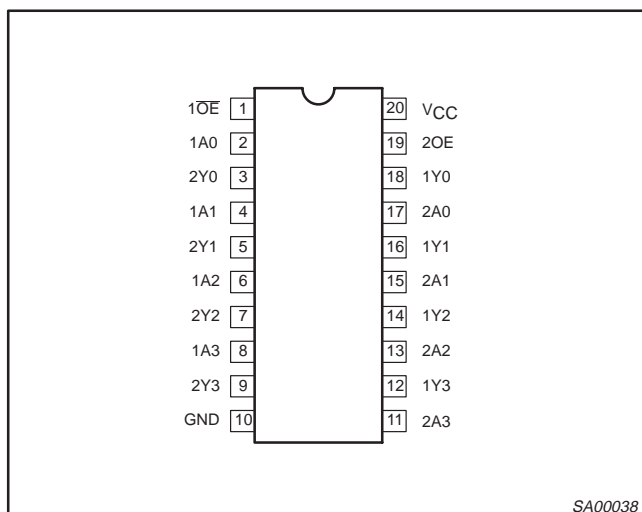
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay An to Yn	C_L = 50pF; V_{CC} = 5V	2.9	ns
C_{IN}	Input capacitance	V_I = 0V or V_{CC}	3	pF
C_{OUT}	Output capacitance	Outputs disabled; V_O = 0V or V_{CC}	7	pF
I_{CCZ}	Total supply current	Outputs disabled; V_{CC} = 5.5V	50	μA

ORDERING INFORMATION

| PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	–40°C to +85°C	74ABT2241 N	74ABT2241 N	SOT146-1
20-Pin plastic SO	–40°C to +85°C	74ABT2241 D	74ABT2241 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74ABT2241 DB	74ABT2241 DB	SOT339-1
20-Pin Plastic TSSOP Type I	–40°C to +85°C	74ABT2241 PW	7ABT2241PW DH	SOT360-1

PIN CONFIGURATION

1$\overline{OE}$	1		20	V_{CC}
1A0	2		19	2OE
2Y0	3		18	1Y0
1A1	4		17	2A0
2Y1	5		16	1Y1
1A2	6		15	2A1
2Y2	7		14	1Y2
1A3	8		13	2A2
2Y3	9		12	1Y3
GND	10		11	2A3

SA00038

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 4, 6, 8	1A0 – 1A3	Data inputs
17, 15, 13, 11	2A0 – 2A3	Data inputs
18, 16, 14, 12	1Y0 – 1Y3	Data outputs
3, 5, 7, 9	2Y0 – 2Y3	Data outputs
1, 19	1$\overline{OE}$, 2OE	Output enables
10	GND	Ground (0V)
20	V_{CC}	Positive supply voltage

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LOGIC SYMBOL (IEEE/IEC)

SA00040

LOGIC SYMBOL

SA00039
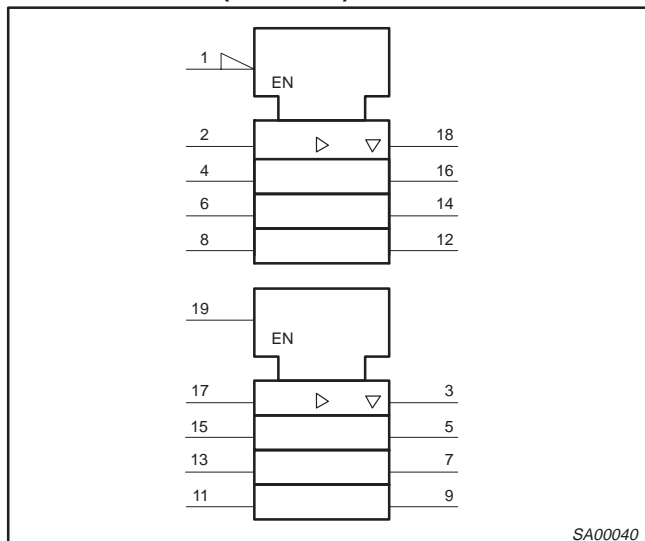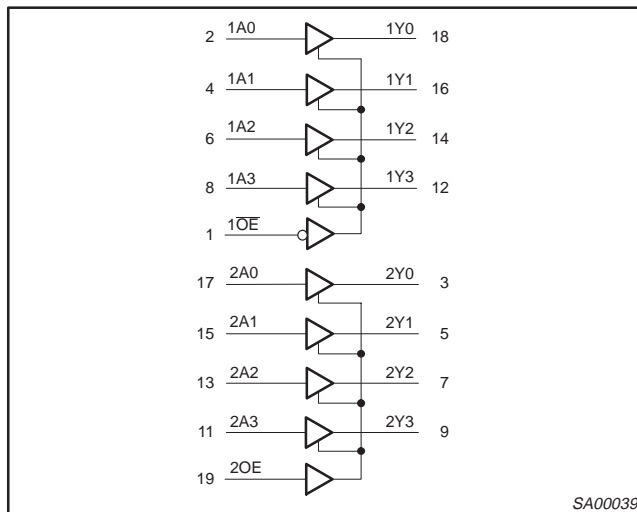
SCHEMATIC OF EACH OUTPUT

SA00409
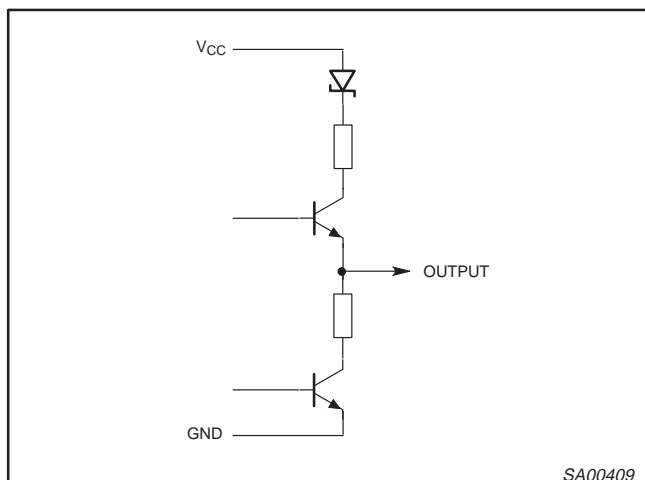
FUNCTION TABLE

INPUTS				OUTPUTS	
1$\overline{\text{OE}}$	1An	2OE	2An	1Yn	2Yn
L	L	H	L	L	L
L	H	H	H	H	H
H	X	L	X	Z	Z

H = High voltage level
L = Low voltage level
X = Don't care
Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		−0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	−18	mA
V_I	DC input voltage[3]		−1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	−50	mA
V_{OUT}	DC output voltage[3]	output in Off or High state	−0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{stg}	Storage temperature range		−65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level Input voltage		0.8	V
I_{OH}	High-level output current		−32	mA
I_{OL}	Low-level output current		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	5	ns/V
T_{amb}	Operating free-air temperature range	−40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			$T_{amb} = +25°C$			$T_{amb} = −40°C$ to +85°C		
			Min	Typ	Max	Min	Max	
V_{IK}	Input clamp voltage	$V_{CC} = 4.5V$; $I_{IK} = −18mA$		−0.9	−1.2		−1.2	V
V_{OH}	High-level output voltage	$V_{CC} = 4.5V$; $I_{OH} = −3mA$; $V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V
		$V_{CC} = 5.0V$; $I_{OH} = −3mA$; $V_I = V_{IL}$ or V_{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5V$; $I_{OH} = −32mA$; $V_I = V_{IL}$ or V_{IH}	2.0	2.4		2.0		V
V_{OL}	Low-level output voltage	$V_{CC} = 4.5V$; $I_{OL} = 5mA$; $V_I = V_{IL}$ or V_{IH}		0.32	0.55		0.55	V
		$V_{CC} = 4.5V$; $I_{OL} = 12mA$; $V_I = V_{IL}$ or V_{IH}			0.8		0.8	V
I_I	Input leakage current	$V_{CC} = 5.5V$; $V_I = GND$ or 5.5V		±0.01	±1.0		±1.0	µA
I_{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_I or $V_O \leq 4.5V$		±5.0	±100		±100	µA
I_{PU}/I_{PD}	Power-up/down 3-State output current[3]	$V_{CC} = 2.0V$; $V_O = 0.5V$; $V_I = GND$ or V_{CC}; $V_{\overline{OE}} = V_{CC}$; $V_{OE} = GND$		±5.0	±50		±50	µA
I_{OZH}	3-State output High current	$V_{CC} = 5.5V$; $V_O = 2.7V$; $V_I = V_{IL}$ or V_{IH}		5.0	50		50	µA
I_{OZL}	3-State output Low current	$V_{CC} = 5.5V$; $V_O = 0.5V$; $V_I = V_{IL}$ or V_{IH}		−5.0	−50		−50	µA
I_{CEX}	Output High leakage current	$V_{CC} = 5.5V$; $V_O = 5.5V$; $V_I = GND$ or V_{CC}		5.0	50		50	µA
I_O	Output current[1]	$V_{CC} = 5.5V$; $V_O = 2.5V$	−50	−100	−180	−50	−180	mA
I_{CCH}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs High, $V_I = GND$ or V_{CC}		50	250		250	µA
I_{CCL}		$V_{CC} = 5.5V$; Outputs Low, $V_I = GND$ or V_{CC}		24	30		30	mA
I_{CCZ}		$V_{CC} = 5.5V$; Outputs 3–State; $V_I = GND$ or V_{CC}		50	250		250	µA
ΔI_{CC}	Additional supply current per input pin[2]	Outputs enabled, one input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$		0.5	1.5		1.5	mA
		Outputs 3-State, one data input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$		50	250		250	µA
		Outputs 3-State, one enable input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$		0.5	1.5		1.5	mA

NOTES:

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1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
2. This is the increase in supply current for each input at 3.4V.
3. This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. For V_{CC} = 2.1V to V_{CC} = 5V $\pm$ 10%, a transition time of up to 100 µsec is permitted.

AC CHARACTERISTICS

GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T_{amb} = +25°C V_{CC} = +5.0V			T_{amb} = −40°C to +85°C V_{CC} = +5.0V ±0.5V		
			Min	Typ	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation delay An to Yn	1	1.0 1.0	2.7 3.9	4.3 5.3	1.0 1.0	4.7 5.6	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	1.1 2.1	3.3 5.4	4.8 7.6	1.1 2.1	5.8 8.4	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low level	2	1.7 1.7	3.8 3.4	5.6 5.8	1.7 1.7	6.6 6.4	ns

AC WAVEFORMS

V_M = 1.5V, V_{IN} = GND to 3.0V
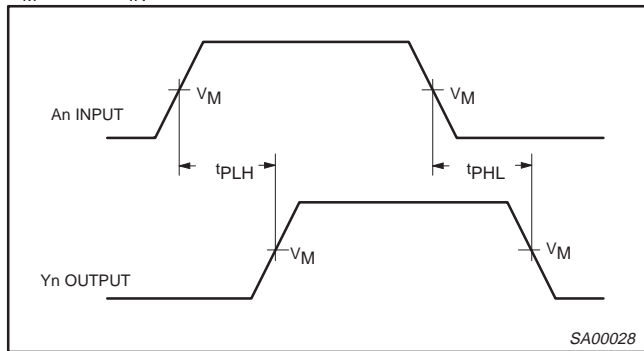
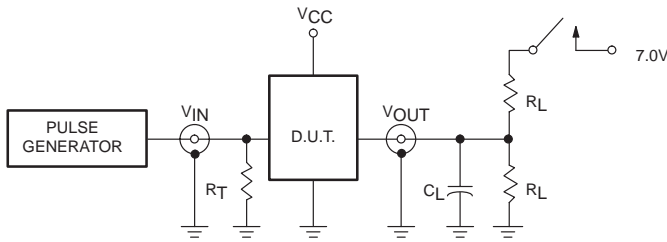**Waveform 1. Waveforms Showing the Input (An) to Output (Yn) Propagation Delays**
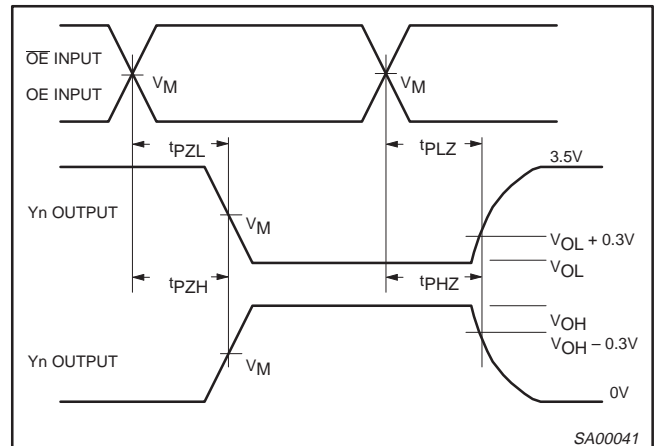
Waveform 2. Waveforms Showing the 3–State Output Enable and Disable Times
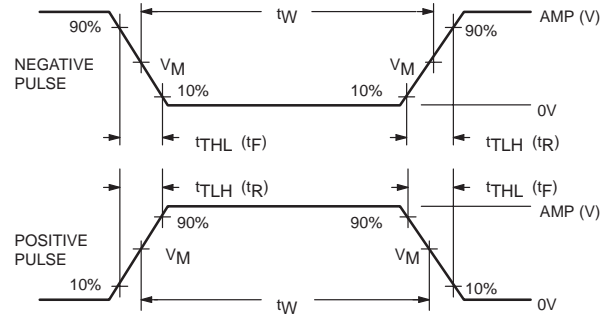
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TEST CIRCUIT AND WAVEFORMS

Test Circuit for 3-State Outputs

SWITCH POSITION

TEST	SWITCH
t_{PLZ}	closed
t_{PZL}	closed
All other	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

Input Pulse Definition

$V_M = 1.5V$

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns

SA00012

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DIP20: plastic dual in-line package; 20 leads (300 mil)   **SOT146-1**
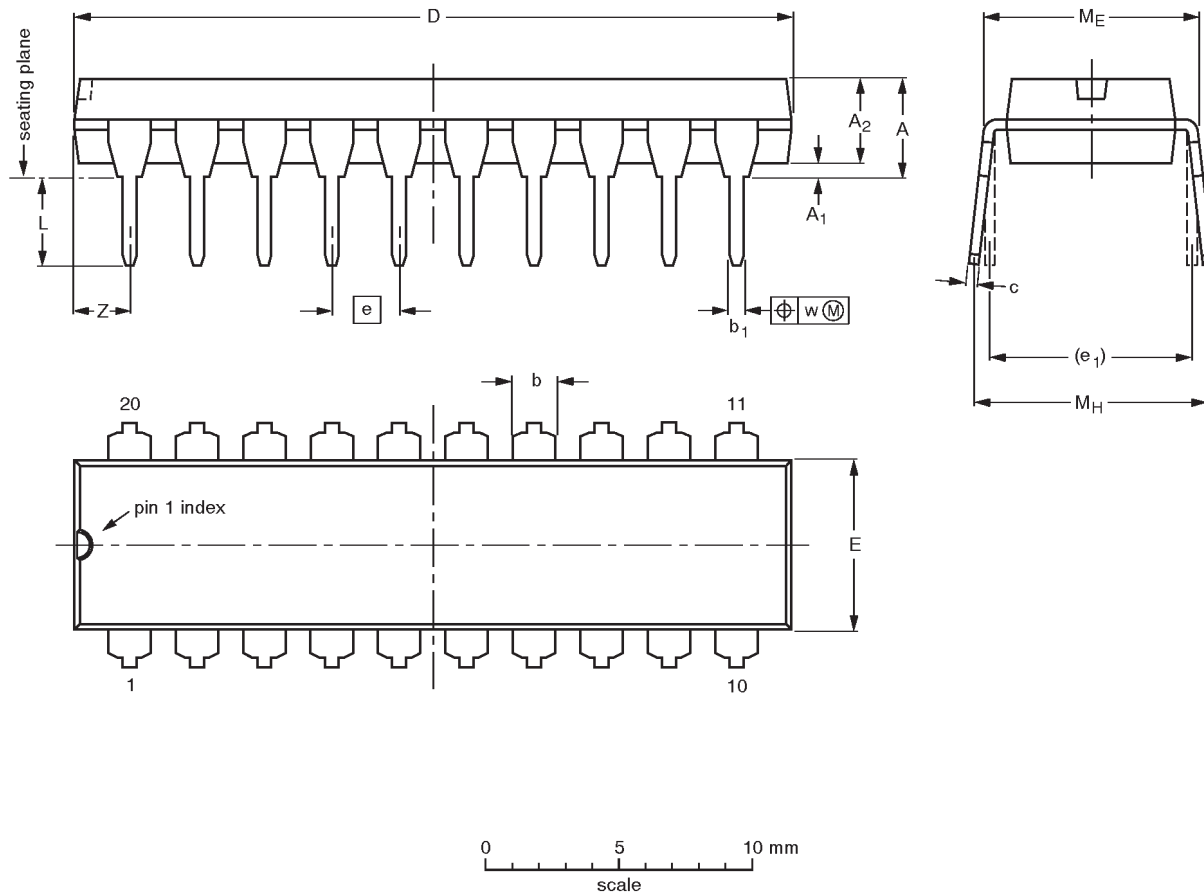
DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A₁ min.	A₂ max.	b	b₁	c	D [1]	E [1]	e	e₁	L	M_E	M_H	w	Z [1] max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~92-11-17~~ 95-01-24

Octal buffer with 30Ω series termination resistors
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SSOP20:   plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1


```
      0        2.5       5 mm
      |__|__|__|__|__|__|__|
              scale
```
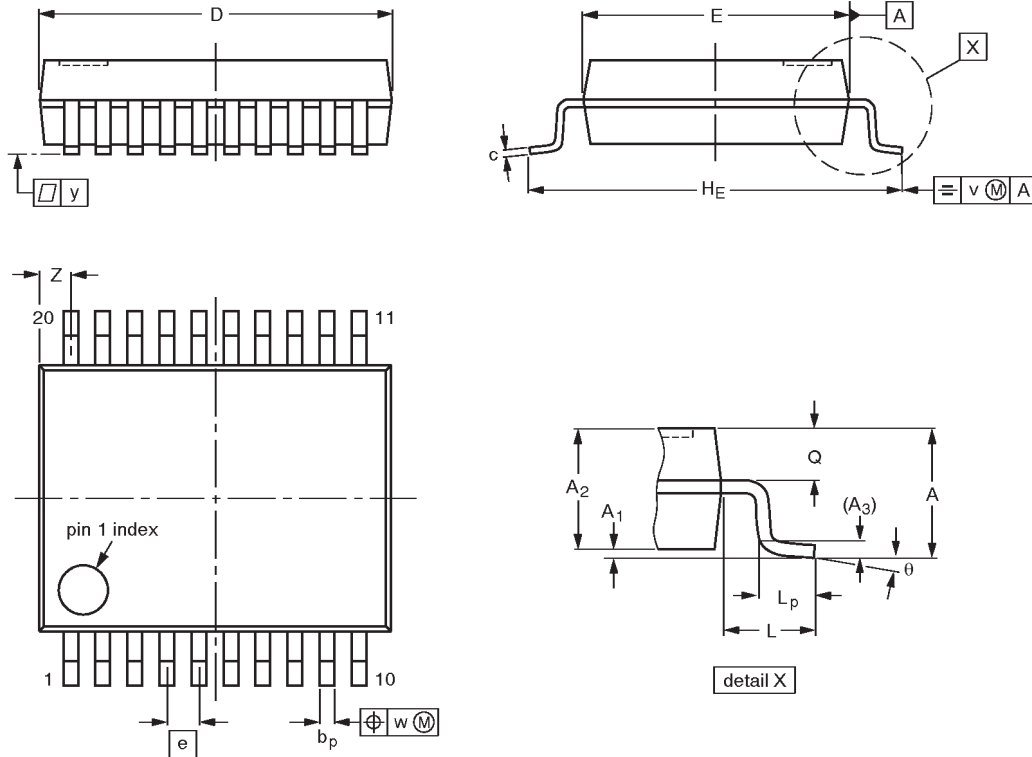
DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A₁	A₂	A₃	bₚ	c	D(1)	E(1)	e	H_E	L	Lₚ	Q	v	w	y	Z(1)	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				~~93-09-08~~ 95-02-04

Octal buffer with 30Ω series termination resistors
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TSSOP20:   plastic thin shrink small outline package; 20 leads; body width 4.4 mm   **SOT360-1**

detail X

```
0        2.5        5 mm
|_|_|_|_|_|_|_|_|_|_|
        scale
```
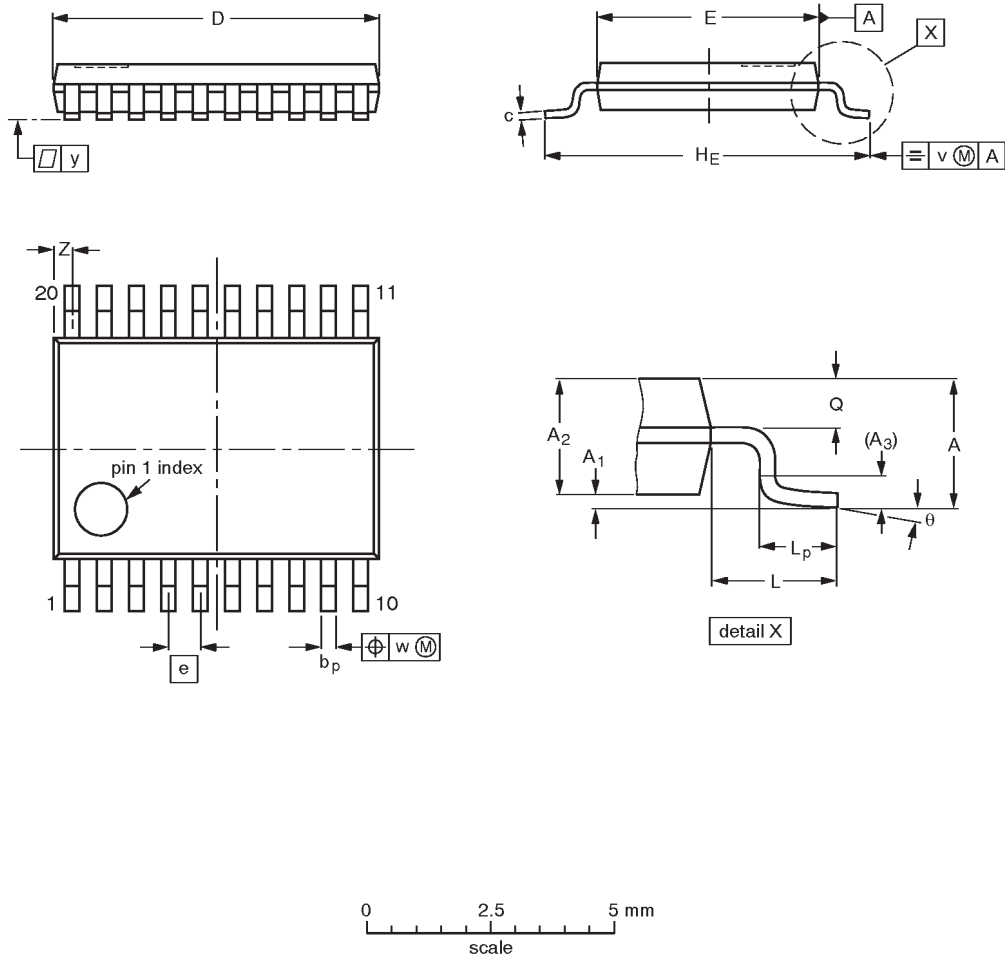
DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D [1]	E [2]	e	H_E	L	L_p	Q	v	w	y	Z [1]	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				~~93-06-16~~ 95-02-04

NOTES

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DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	**Formative or in Design**	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	**Preproduction Product**	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	**Full Production**	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.